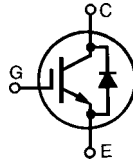


# HiPerFAST™ IGBT Lightspeed™ Series

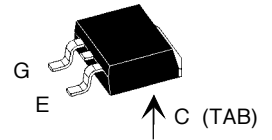
IXGA 12N60CD1  
IXGP 12N60CD1

$V_{CES} = 600\text{ V}$   
 $I_{C25} = 24\text{ A}$   
 $V_{CE(sat)} = 2.7\text{ V}$   
 $t_{fi(typ)} = 55\text{ ns}$

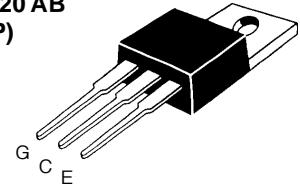


Symbol	Test Conditions	Maximum Ratings	
$V_{CES}$	$T_J = 25^\circ\text{C to } 150^\circ\text{C}$	600	V
$V_{CGR}$	$T_J = 25^\circ\text{C to } 150^\circ\text{C}; R_{GE} = 1\text{ M}\Omega$	600	V
$V_{GES}$	Continuous	$\pm 20$	V
$V_{GEM}$	Transient	$\pm 30$	V
$I_{C25}$	$T_C = 25^\circ\text{C}$	24	A
$I_{C90}$	$T_C = 90^\circ\text{C}$	12	A
$I_{CM}$	$T_C = 25^\circ\text{C}, 1\text{ ms}$	48	A
<b>SSOA (RBSOA)</b>	$V_{GE} = 15\text{ V}, T_{VJ} = 125^\circ\text{C}, R_G = 33\ \Omega, I_{CM} = 24\text{ A}$ Clamped inductive load, $L = 300\ \mu\text{H}$	$@ 0.8 V_{CES}$	
$P_C$	$T_C = 25^\circ\text{C}$	100	W
$T_J$		-55 ... +150	$^\circ\text{C}$
$T_{JM}$		150	$^\circ\text{C}$
$T_{stg}$		-55 ... +150	$^\circ\text{C}$
$M_d$	Mounting torque with screw M3	0.45/4	Nm/lb.in.
	Mounting torque with screw M3.5	0.55/5	Nm/lb.in.
<b>Weight</b>		4	g
Maximum lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s		300	$^\circ\text{C}$

## TO-263 (IXGA)



## TO-220 AB (IXGP)



G = Gate      C = Collector  
E = Emitter    TAB = Collector

## Features

- Very high frequency IGBT
- New generation HDMOS™ process
- International standard package  
JEDEC TO-220AB and TO-263AA
- High peak current handling capability

## Applications

- PFC circuit
- AC motor speed control
- DC servo and robot drives
- Switch-mode and resonant-mode power supplies
- High power audio amplifiers

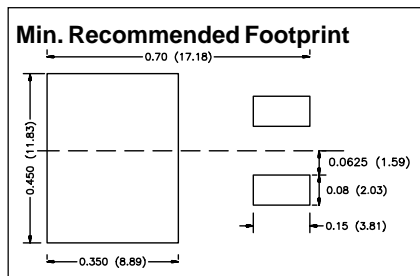
## Advantages

- Fast switching speed
- High power density

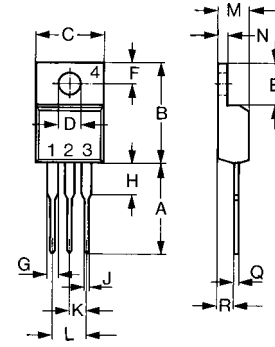
Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$BV_{CES}$	$I_C = 250\ \mu\text{A}, V_{GE} = 0\text{ V}$	600		V
$V_{GE(th)}$	$I_C = 250\ \mu\text{A}, V_{GE} = V_{CE}$	2.5		V
$I_{CES}$	$V_{CE} = 0.8 V_{CES}$ $V_{GE} = 0\text{ V}$		$T_J = 25^\circ\text{C}$	200 $\mu\text{A}$
			$T_J = 125^\circ\text{C}$	1.5 mA
$I_{GES}$	$V_{CE} = 0\text{ V}, V_{GE} = \pm 20\text{ V}$			$\pm 100\text{ nA}$
$V_{CE(sat)}$	$I_C = I_{CE90}, V_{GE} = 15\text{ V}$	2.1	2.7	V

Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$g_{fs}$	$I_C = I_{C90}$ ; $V_{CE} = 10\text{ V}$ , Pulse test, $t \leq 300\ \mu\text{s}$ , duty cycle $\leq 2\%$	5	11	S
$C_{ies}$	$V_{CE} = 25\text{ V}$ , $V_{GE} = 0\text{ V}$ , $f = 1\text{ MHz}$		860	pF
$C_{oes}$			100	pF
$C_{res}$			15	pF
$Q_g$	$I_C = I_{C90}$ , $V_{GE} = 15\text{ V}$ , $V_{CE} = 0.5\text{ V}_{CES}$		32	nC
$Q_{ge}$			10	nC
$Q_{gc}$			10	nC
$t_{d(on)}$	<b>Inductive load, <math>T_J = 25^\circ\text{C}</math></b> $I_C = I_{C90}$ , $V_{GE} = 15\text{ V}$ , $L = 300\ \mu\text{H}$ $V_{CE} = 0.8\text{ V}_{CES}$ , $R_G = R_{off} = 18\ \Omega$ Remarks: Switching times may increase for $V_{CE}(\text{Clamp}) > 0.8\text{ V}_{CES}$ , higher $T_J$ or increased $R_G$		20	ns
$t_{ri}$			20	ns
$t_{d(off)}$			60	ns
$t_{fi}$			55	ns
$E_{off}$			0.09	mJ
$t_{d(on)}$	<b>Inductive load, <math>T_J = 125^\circ\text{C}</math></b> $I_C = I_{C90}$ , $V_{GE} = 15\text{ V}$ , $L = 300\ \mu\text{H}$ $V_{CE} = 0.8\text{ V}_{CES}$ , $R_G = R_{off} = 18\ \Omega$ Remarks: Switching times may increase for $V_{CE}(\text{Clamp}) > 0.8\text{ V}_{CES}$ , higher $T_J$ or increased $R_G$		20	ns
$t_{ri}$			20	ns
$E_{on}$			0.5	mJ
$t_{d(off)}$			85	180 ns
$t_{fi}$			85	180 ns
$E_{off}$			0.27	0.60 mJ
$R_{thJC}$	IGBT			1.25 K/W
$R_{thCK}$		0.25		K/W

Symbol	Test Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$V_F$	$I_F = 15\text{ A}$ ; $T_{VJ} = 150^\circ\text{C}$ $T_{VJ} = 25^\circ\text{C}$		1.7	2.5 V
$I_{RM}$	$V_R = 100\text{ V}$ ; $I_F = 25\text{ A}$ ; $-di_F/dt = 100\text{ A}/\mu\text{s}$ $L \leq 0.05\ \mu\text{H}$ ; $T_{VJ} = 100^\circ\text{C}$		2	2.5 A
$t_{rr}$	$I_F = 1\text{ A}$ ; $-di/dt = 50\text{ A}/\mu\text{s}$ ; $V_R = 30\text{ V}$ ; $T_J = 25^\circ\text{C}$		35	ns
$R_{thJC}$	Diode			1.6 K/W

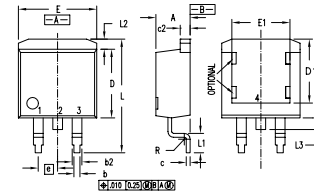


### TO-220 AB (IXGP) Outline



Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	12.70	13.97	0.500	0.550
B	14.73	16.00	0.580	0.630
C	9.91	10.66	0.390	0.420
D	3.54	4.08	0.139	0.161
E	5.85	6.85	0.230	0.270
F	2.54	3.18	0.100	0.125
G	1.15	1.65	0.045	0.065
H	2.79	5.84	0.110	0.230
J	0.64	1.01	0.025	0.040
K	2.54	BSC	0.100	BSC
M	4.32	4.82	0.170	0.190
N	1.14	1.39	0.045	0.055
Q	0.35	0.56	0.014	0.022
R	2.29	2.79	0.090	0.110

### TO-263 AA (IXGA) Outline



Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.06	4.83	.160	.190
A1	2.03	2.79	.080	.110
b	0.51	0.99	.020	.039
b2	1.14	1.40	.045	.055
c	0.46	0.74	.018	.029
c2	1.14	1.40	.045	.055
D	8.64	9.65	.340	.380
D1	7.11	8.13	.280	.320
E	9.65	10.29	.380	.405
E1	6.86	8.13	.270	.320
e	2.54	BSC	.100	BSC
L	14.61	15.88	.575	.625
L1	2.29	2.79	.090	.110
L2	1.02	1.40	.040	.055
L3	1.27	1.78	.050	.070
L4	0	0.38	0	.015
R	0.46	0.74	.018	.029

IXYS reserves the right to change limits, test conditions, and dimensions.